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#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

-XF

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	224 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 5x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf15313-i-rf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## 2.0 GUIDELINES FOR GETTING STARTED WITH PIC16(L)F15313/23 MICROCONTROLLERS

### 2.1 Basic Connection Requirements

Getting started with the PIC16(L)F15313/23 family of 8bit microcontrollers requires attention to a minimal set of device pin connections before proceeding with development.

The following pins must always be connected:

All VDD and VSS pins (see Section 2.2 "Power Supply Pins")
MCLR pin

(see Section 2.3 "Master Clear (MCLR) Pin")

These pins must also be connected if they are being used in the end application:

- ICSPCLK/ICSPDAT pins used for In-Circuit Serial Programming<sup>™</sup> (ICSP<sup>™</sup>) and debugging purposes (see **Section 2.4 "ICSP<sup>™</sup> Pins**")
- OSCI and OSCO pins when an external oscillator source is used

(see Section 2.5 "External Oscillator Pins")

Additionally, the following pins may be required:

• VREF+/VREF- pins are used when external voltage reference for analog modules is implemented

The minimum mandatory connections are shown in Figure 2-1.

#### FIGURE 2-1: RECOMMENDED MINIMUM CONNECTIONS



## 2.2 Power Supply Pins

## 2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins (VDD and VSS) is required.

Consider the following criteria when using decoupling capacitors:

- Value and type of capacitor: A 0.1  $\mu$ F (100 nF), 10-25V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- Placement on the printed circuit board: The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- Handling high-frequency noise: If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01  $\mu$ F to 0.001  $\mu$ F. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1  $\mu$ F in parallel with 0.001  $\mu$ F).
- Maximizing performance: On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

## 2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7  $\mu$ F to 47  $\mu$ F.

	ABEL 4-10. SI EGIAE I ONCHON REGISTER SOMMART BANKS 0-03 (CONTINUED)										
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	V <u>alue o</u> n: MCLR
Bank 60 (C	continued)										
1E2Bh	CLC3GLS1	LC3G2D4T	LC3G4D3N	LC3G2D3T	LC3G2D3N	LC3G2D2T	LC3G2D2N	LC3G2D1T	LC3G2D1N	XXXX XXXX	uuuu uuuu
1E2Ch	CLC3GLS2	LC3G3D4T	LC3G4D3N	LC3G3D3T	LC3G3D3N	LC3G3D2T	LC3G3D2N	LC3G3D1T	LC3G3D1N	XXXX XXXX	uuuu uuuu
1E2Dh	CLC3GLS3	LC3G4D4T	LC3G4D3N	LC3G4D3T	LC3G4D3N	LC3G4D2T	LC3G4D2N	LC3G4D1T	LC3G4D1N	XXXX XXXX	uuuu uuuu
1E2Eh	CLC4CON	LC4EN	—	LC4OUT	LC4INTP LC4INTN LC4MODE<2:0>					0-00 0000	0-00 0000
1E2Fh	CLC4POL	LC4POL	—	—	—	LC4G4POL	LC4G3POL	LC4G2POL	LC4G1POL	0 xxxx	0 uuuu
1E30h	CLC4SEL0	—	—			xx xxxx	uu uuuu				
1E31h	CLC4SEL1	—	—			LC4E	02S<5:0>			xx xxxx	uu uuuu
1E32h	CLC4SEL2	—	—			LC4E	03S<5:0>			xx xxxx	uu uuuu
1E33h	CLC4SEL3	—	—			LC4E	04S<5:0>			xx xxxx	uu uuuu
1E34h	CLC4GLS0	LC4G1D4T	LC4G4D3N	LC4G1D3T	LC4G1D3N	LC4G1D2T	LC4G1D2N	LC4G1D1T	LC4G1D1N	XXXX XXXX	uuuu uuuu
1E35h	CLC4GLS1	LC4G2D4T	LC4G4D3N	LC4G2D3T	LC4G2D3N	LC4G2D2T	LC4G2D2N	LC4G2D1T	LC4G2D1N	XXXX XXXX	uuuu uuuu
1E36h	CLC4GLS2	LC4G3D4T	LC4G4D3N	LC4G3D3T	LC4G3D3N	LC4G3D2T	LC4G3D2N	LC4G3D1T	LC4G3D1N	XXXX XXXX	uuuu uuuu
1E37h	CLC4GLS3	LC4G4D4T	LC4G4D3N	LC4G4D3T	LC4G4D3N	LC4G4D2T	LC4G4D2N	LC4G4D1T	LC4G4D1N	xxxx xxxx	uuuu uuuu
1E38h —	_	Unimplemented							_	_	
1E6Fh											

### TABLE 4-10: SPECIAL FUNCTION REGISTER SUMMARY BANKS 0-63 (CONTINUED)

Legend: x = unknown, u = unchanged, g = depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

### FIGURE 9-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



- Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.
  - 2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.
  - **3:** For oscillator design assistance, reference the following Microchip Application Notes:
    - AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC<sup>®</sup> and PIC<sup>®</sup> Devices" (DS00826)
    - AN849, "Basic PIC<sup>®</sup> Oscillator Design" (DS00849)
    - AN943, "Practical PIC<sup>®</sup> Oscillator Analysis and Design" (DS00943)
    - AN949, "Making Your Oscillator Work" (DS00949)

## FIGURE 9-4:

#### CERAMIC RESONATOR OPERATION (XT OR HS MODE)



## 9.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR), Brown-out Reset (BOR) or a wake-up from Sleep. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

#### 13.3.4 NVMREG WRITE TO PROGRAM MEMORY

Program memory is programmed using the following steps:

- 1. Load the address of the row to be programmed into NVMADRH:NVMADRL.
- 2. Load each write latch with data.
- 3. Initiate a programming operation.
- 4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 13-4 (row writes to program memory with 32 write latches) for more details.

The write latches are aligned to the Flash row address boundary defined by the upper ten bits of NVMADRH:NVMADRL, (NVMADRH<6:0>:NVMADRL<7:5>) with the lower five bits of NVMADRL, (NVMADRL<4:0>) determining the write latch being loaded. Write operations do not cross these boundaries. At the completion of a program memory write operation, the data in the write latches is reset to contain 0x3FFF. The following steps should be completed to load the write latches and program a row of program memory. These steps are divided into two parts. First, each write latch is loaded with data from the NVMDATH:NVMDATL using the unlock sequence with LWLO = 1. When the last word to be loaded into the write latch is ready, the LWLO bit is cleared and the unlock sequence executed. This initiates the programming operation, writing all the latches into Flash program memory.

- Note: The special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. If the unlock sequence is interrupted, writing to the latches or program memory will not be initiated.
- 1. Set the WREN bit of the NVMCON1 register.
- 2. Clear the NVMREGS bit of the NVMCON1 register.
- Set the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
- 4. Load the NVMADRH:NVMADRL register pair with the address of the location to be written.
- 5. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
- Execute the unlock sequence (Section 13.3.2 "NVM Unlock Sequence"). The write latch is now loaded.
- 7. Increment the NVMADRH:NVMADRL register pair to point to the next location.
- 8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
- Clear the LWLO bit of the NVMCON1 register. When the LWLO bit of the NVMCON1 register is '0', the write sequence will initiate the write to Flash program memory.
- 10. Load the NVMDATH:NVMDATL register pair with the program memory data to be written.
- Execute the unlock sequence (Section 13.3.2 "NVM Unlock Sequence"). The entire program memory latch content is now written to Flash program memory.

An example of the complete write sequence is shown in Example 13-4. The initial address is loaded into the NVMADRH:NVMADRL register pair; the data is loaded using indirect addressing.

Note: The program memory write latches are reset to the blank state (0x3FFF) at the completion of every write or erase operation. As a result, it is not necessary to load all the program memory write latches. Unloaded latches will remain in the blank state.

#### EXAMPLE 13-4: WRITING TO PROGRAM FLASH MEMORY

; This	write routine	e assumes the following:	
; 1.6	4 bytes of dat	a are loaded, starting a	at the address in DATA_ADDR
; 2. E	ach word of da	ta to be written is made	e up of two adjacent bytes in DATA_ADDR,
; s	tored in littl	e endian format	
; 3.A	valid startin	ng address (the least sig	gnificant bits = 00000) is loaded in ADDRH:ADDRL
; 4. A	DDRH and ADDRL	are located in common F	RAM (locations 0x70 - 0x7F)
; 5. N	VM interrupts	are not taken into accou	int
	BANKSEL	NVMADRH	
	MOVF	ADDRH,W	
	MOVWF	NVMADRH	; Load initial address
	MOVF	ADDRL,W	
	MOVWF	NVMADRL	
	MOVLW	LOW DATA_ADDR	; Load initial data address
	MOVWF	FSROL	
	MOVLW	HIGH DATA_ADDR	
	MOVWF	FSROH	
	BCF	NVMCON1,NVMREGS	; Set Program Flash Memory as write location
	BSF	NVMCON1,WREN	; Enable writes
	BSF	NVMCON1,LWLO	; Load only write latches
LOOP			
	MOVIW	FSR0++	
	MOVWF	NVMDATL	; Load first data byte
	MOVIW	FSR0++	
	MOVWF	NVMDATH	; Load second data byte
	MOVF	NVMADRL,W	
	XORLW	0x1F	; Check if lower bits of address are 00000
	ANDLW	0x1F	; and if on last of 32 addresses
	BTFSC	STATUS, Z	; Last of 32 words?
	GOTO	START_WRITE	; If so, go write latches into memory
	CALL	UNLOCK_SEQ	; If not, go load latch
	INCF	NVMADRL, F	; Increment address
	GOTO	LOOP	
START	WRITE		
~	BCF	NVMCON1, LWLO	; Latch writes complete, now write memory
	CALL	UNLOCK SEO	; Perform required unlock sequence
	BCF	NVMCON1, WREN	; Disable writes
	CEO.		
UNLOCK	L_SEQ MOVI W	5 5 b	
	MOVIN	INTCON CIE	· Dicable interrupta
	MOVWE	INTCON, GIE	· Disable interrupts
	MOVWF	A A b	, Begin unioek sequence
	MOVWE	NVMCON2	
	BSF	NVMCON1.WR	
	BSF	INTCON GIE	; Unlock sequence complete re-enable interrunts
	return	INTON, GIE	, ontook bequence comprete, re-enable interrupts
	TCCUTH		

## 26.6 Timer1 Interrupts

The timer register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When the timer rolls over, the respective timer interrupt flag bit of the PIR5 register is set. To enable the interrupt on rollover, you must set these bits:

- ON bit of the T1CON register
- TMR1IE bit of the PIE4 register
- PEIE bit of the INTCON register
- GIE bit of the INTCON register

The interrupt is cleared by clearing the TMR1IF bit in the Interrupt Service Routine.

Note:	To avoid immediate interrupt vectoring,
	the TMR1H:TMR1L register pair should
	be preloaded with a value that is not immi-
	nently about to rollover, and the TMR1IF
	flag should be cleared prior to enabling
	the timer interrupts.

## 26.7 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To set up the timer to wake the device:

- · ON bit of the T1CON register must be set
- TMR1IE bit of the PIE4 register must be set
- · PEIE bit of the INTCON register must be set
- · SYNC bit of the T1CON register must be set
- CS bits of the T1CLK register must be configured
- The timer clock source must be enabled and continue operation during sleep.

The device will wake-up on an overflow and execute the next instructions. If the GIE bit of the INTCON register is set, the device will call the Interrupt Service Routine.

### 26.8 CCP Capture/Compare Time Base

The CCP modules use the TMR1H:TMR1L register pair as the time base when operating in Capture or Compare mode.

In Capture mode, the value in the TMR1H:TMR1L register pair is copied into the CCPRxH:CCPRxL register pair on a configured event.

In Compare mode, an event is triggered when the value CCPRxH:CCPRxL register pair matches the value in the TMR1H:TMR1L register pair. This event can be an Auto-conversion Trigger.

For more information, see Section 28.0 "Capture/Compare/PWM Modules".

## 26.9 CCP Auto-Conversion Trigger

When any of the CCP's are configured to trigger an auto-conversion, the trigger will clear the TMR1H:TMR1L register pair. This auto-conversion does not cause a timer interrupt. The CCP module may still be configured to generate a CCP interrupt.

In this mode of operation, the CCPRxH:CCPRxL register pair becomes the period register for Timer1.

The timer should be synchronized and FOSC/4 should be selected as the clock source in order to utilize the Auto-conversion Trigger. Asynchronous operation of the timer can cause an Auto-conversion Trigger to be missed.

In the event that a write to TMR1H or TMR1L coincides with an Auto-conversion Trigger from the CCP, the write will take precedence.

For more information, see Section 28.2.4 "Compare During Sleep".

## 27.0 TIMER2 MODULE WITH HARDWARE LIMIT TIMER (HLT)

The Timer2 module is an 8-bit timer that can operate as free-running period counters or in conjunction with external signals that control start, run, freeze, and reset operation in One-Shot and Monostable modes of operation. Sophisticated waveform control such as pulse density modulation are possible by combining the operation of this timer with other internal peripherals such as the comparators and CCP modules. Features of the timer include:

- 8-bit timer register
- 8-bit period register

- · Selectable external hardware timer Resets
- Programmable prescaler (1:1 to 1:128)
- Programmable postscaler (1:1 to 1:16)
- · Selectable synchronous/asynchronous operation
- Alternate clock sources
- Interrupt-on-period
- · Three modes of operation:
  - Free Running Period
  - One-shot
  - Monostable

See Figure 27-1 for a block diagram of Timer2. See Figure 27-2 for the clock source block diagram.



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#### 30.1.4 STEERING MODES

In Steering modes, the data input can be steered to any or all of the four CWG output pins. In Synchronous Steering mode, changes to steering selection registers take effect on the next rising input.

In Non-Synchronous mode, steering takes effect on the next instruction cycle. Additional details are provided in **Section 30.9 "CWG Steering Mode"**.





## 30.2 Clock Source

The CWG module allows the following clock sources to be selected:

- Fosc (system clock)
- HFINTOSC (16 MHz only)

The clock sources are selected using the CS bit of the CWG1CLKCON register.

U-0	U-0	R-x	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	_	IN	—	POLD	POLC	POLB	POLA
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimplei	mented bit, read	as '0'	
u = Bit is unch	anged	x = Bit is unkr	iown	-n/n = Value	at POR and BO	R/Value at all o	other Resets
'1' = Bit is set		'0' = Bit is clea	ared	q = Value de	pends on condit	ion	
bit 7-6	Unimplemen	ted: Read as '	כ'				
bit 5	IN: CWG Inpu	ut Value bit					
bit 4	Unimplemen	ted: Read as '	o'				
bit 3	POLD: CWG	1D Output Pola	rity bit				
	1 = Signal ou	utput is inverted	l polarity				
	0 = Signal ou	utput is normal	polarity				
bit 2	POLC: CWG	1C Output Pola	rity bit				
	1 = Signal ou	Itput is inverted	l polarity				
		Itput is normal	polarity				
bit 1	POLB: CWG1B Output Polarity bit						
	1 = Signal output is inverted polarity						
hit 0			pulanty				
		TA Output Pola	inty Dit Lociority				
	1 = Signal of 0 = Signal of 0	utput is inverted	polarity				

## REGISTER 30-2: CWG1CON1: CWG1 CONTROL REGISTER 1

### TABLE 30-3:SUMMARY OF REGISTERS ASSOCIATED WITH CWG

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CWG1CLKCON	_	_	_	—	—	—	_	CS	341
CWG1ISM	_	_	_	_		IS<	<3:0>		341
CWG1DBR	_	_			DBR	<5:0>			337
CWG1DBF	_	_		_	DBF	<5:0>			337
CWG1CON0	EN	LD	_	_	_		MODE<2:0>		340
CWG1CON1	_	_	IN	_	POLD	POLC	POLB	POLA	336
CWG1AS0	SHUTDOWN	REN	LSBD<1:0> LSAC<1:0> — —					338	
CWG1AS1	_	_	_	AS4E	AS3E	AS2E	AS1E	AS0E	339
CWG1STR	OVRD	OVRC	OVRB	OVRA	STRD	STRC	STRB	STRA	340

Legend: -= unimplemented locations read as '0'. Shaded cells are not used by CWG.

# PIC16(L)F15313/23



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R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG3D4T	LCxG3D4N	LCxG3D3T	LCxG3D3N	LCxG3D2T	LCxG3D2N	LCxG3D1T	LCxG3D1N
bit 7							bit 0
Legend:							
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'	
u = Bit is unch	anged	x = Bit is unkr	nown	-n/n = Value a	at POR and BO	R/Value at all c	ther Resets
'1' = Bit is set		'0' = Bit is clea	ared				
bit 7	LCxG3D4T: (	Gate 2 Data 4 1	rue (non-inve	rted) bit			
	1 = CLCIN3	(true) is gated i	nto CLCx Gat	e 2 Cata 2			
hit 6	0 = CLCIN3(	(true) is not gai	Negated (inve	Gale Z			
DILO	1 = CLCIN3	(inverted) is a	ted into CLCx	Gate 2			
	0 = CLCIN3	(inverted) is no	t gated into CL	_Cx Gate 2			
bit 5	LCxG3D3T:	Gate 2 Data 3 1	rue (non-inve	rted) bit			
	1 = CLCIN2 (	(true) is gated i	nto CLCx Gate	e 2			
	0 = CLCIN2	(true) is not gat	ed into CLCx	Gate 2			
bit 4	LCxG3D3N:	Gate 2 Data 3	Negated (inver	rted) bit			
	1 = CLCIN2 0 = CLCIN2	(inverted) is ga (inverted) is no	ted into CLCx t gated into CI	Gate 2 Cx Gate 2			
bit 3	LCxG3D2T: (	Gate 2 Data 2 1	rue (non-inve	rted) bit			
	1 = CLCIN1 (	(true) is gated i	nto CLCx Gat	e 2			
	0 = CLCIN1 (	(true) is not gat	ted into CLCx	Gate 2			
bit 2	LCxG3D2N:	Gate 2 Data 2 I	Negated (inver	rted) bit			
	1 = CLCIN1	(inverted) is ga	ted into CLCx	Gate 2			
	0 = CLCIN1 (	(inverted) is no	t gated into Cl	Cx Gate 2			
bit 1 LCxG3D1T: Gate 2 Data 1 True (non-inverted)							
	1 = CLCINU( 0 = CLCINU(	(true) is gated i (true) is not gat	nto CLCX Gate	e z Gate 2			
bit 0	LCxG3D1N:	Gate 2 Data 1 I	Negated (inve	rted) bit			
	1 = CLCIN0 (	(inverted) is ga	ted into CLCx	Gate 2			
	0 = CLCINO	(inverted) is no	t gated into CL	_Cx Gate 2			

## REGISTER 31-9: CLCxGLS2: GATE 2 LOGIC SELECT REGISTER

The  $\mathsf{I}^2\mathsf{C}$  interface supports the following modes and features:

- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- · Limited multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking

- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- · Selectable SDA hold times

Figure 32-2 is a block diagram of the  $I^2C$  interface module in Master mode. Figure 32-3 is a diagram of the  $I^2C$  interface module in Slave mode.

## FIGURE 32-2: MSSP BLOCK DIAGRAM (I<sup>2</sup>C MASTER MODE)







### 32.2.1 SPI MODE REGISTERS

The MSSP module has five registers for SPI mode operation. These are:

- MSSP STATUS register (SSP1STAT)
- MSSP Control register 1 (SSP1CON1)
- MSSP Control register 3 (SSP1CON3)
- MSSP Data Buffer register (SSP1BUF)
- MSSP Address register (SSP1ADD)
- MSSP Shift register (SSP1SR) (Not directly accessible)

SSP1CON1 and SSP1STAT are the control and status registers in SPI mode operation. The SSP1CON1 register is readable and writable. The lower six bits of the SSP1STAT are read-only. The upper two bits of the SSP1STAT are read/write.

In one SPI master mode, SSP1ADD can be loaded with a value used in the Baud Rate Generator. More information on the Baud Rate Generator is available in **Section 32.7 "Baud Rate Generator"**.

SSP1SR is the shift register used for shifting data in and out. SSP1BUF provides indirect access to the SSP1SR register. SSP1BUF is the buffer register to which data bytes are written, and from which data bytes are read.

In receive operations, SSP1SR and SSP1BUF together create a buffered receiver. When SSP1SR receives a complete byte, it is transferred to SSP1BUF and the SSP1IF interrupt is set.

During transmission, the SSP1BUF is not buffered. A write to SSP1BUF will write to both SSP1BUF and SSP1SR.

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#### 32.5.8 GENERAL CALL ADDRESS SUPPORT

The addressing procedure for the  $I^2C$  bus is such that the first byte after the Start condition usually determines which device will be the slave addressed by the master device. The exception is the general call address which can address all devices. When this address is used, all devices should, in theory, respond with an acknowledge.

The general call address is a reserved address in the  $I^2C$  protocol, defined as address  $0 \ge 0.00$ . When the GCEN bit of the SSP1CON2 register is set, the slave module will automatically ACK the reception of this address regardless of the value stored in SSP1ADD. After the slave clocks in an address of all zeros with the R/W bit clear, an interrupt is generated and slave software can read SSP1BUF and respond. Figure 32-24 shows a general call reception sequence.

In 10-bit Address mode, the UA bit will not be set on the reception of the general call address. The slave will prepare to receive the second byte as data, just as it would in 7-bit mode.

If the AHEN bit of the SSP1CON3 register is set, just as with any other address reception, the slave hardware will stretch the clock after the eighth falling edge of SCL. The slave must then set its ACKDT value and release the clock with communication progressing as it would normally.





32.5.9 SSP MASK REGISTER

An SSP Mask (SSP1MSK) register (Register 32-5) is available in I<sup>2</sup>C Slave mode as a mask for the value held in the SSP1SR register during an address comparison operation. A zero ('0') bit in the SSP1MSK register has the effect of making the corresponding bit of the received address a "don't care". This register is reset to all '1's upon any Reset condition and, therefore, has no effect on standard SSP operation until written with a mask value.

The SSP Mask register is active during:

- 7-bit Address mode: address compare of A<7:1>.
- 10-bit Address mode: address compare of A<7:0> only. The SSP mask has no effect during the reception of the first (high) byte of the address.

## 32.6.13.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

- a) A low level is sampled on SDA when SCL goes from low level to high level (Case 1).
- b) SCL goes low before SDA is asserted low, indicating that another master is attempting to transmit a data '1' (Case 2).

When the user releases SDA and the pin is allowed to float high, the BRG is loaded with SSP1ADD and counts down to zero. The SCL pin is then deasserted and when sampled high, the SDA pin is sampled.

If SDA is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', Figure 32-36). If SDA is sampled high, the BRG is reloaded and begins

counting. If SDA goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDA at exactly the same time.

If SCL goes from high-to-low before the BRG times out and SDA has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition, see Figure 32-37.

If, at the end of the BRG time-out, both SCL and SDA are still high, the SDA pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCL pin, the SCL pin is driven low and the Repeated Start condition is complete.





#### FIGURE 32-37: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



#### R/W-0/0 R/W-0/0 R/W-0/0 R/W-0/0 R/W-0/0 R/W-0/0 R/W-0/0 R-0/0 ACKTIM<sup>(3)</sup> PCIE SCIE BOEN SBCDE AHEN DHEN SDAHT bit 7 bit 0 Legend: R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets '1' = Bit is set '0' = Bit is cleared bit 7 ACKTIM: Acknowledge Time Status bit (I<sup>2</sup>C mode only)<sup>(3)</sup> 1 = Indicates the I<sup>2</sup>C bus is in an Acknowledge sequence, set on 8<sup>th</sup> falling edge of SCL clock 0 = Not an Acknowledge sequence, cleared on $9^{TH}$ rising edge of SCL clock **PCIE**: Stop Condition Interrupt Enable bit (I<sup>2</sup>C mode only) bit 6 1 = Enable interrupt on detection of Stop condition 0 = Stop detection interrupts are disabled<sup>(2)</sup> SCIE: Start Condition Interrupt Enable bit (I<sup>2</sup>C mode only) bit 5 1 = Enable interrupt on detection of Start or Restart conditions 0 = Start detection interrupts are disabled<sup>(2)</sup> BOEN: Buffer Overwrite Enable bit bit 4 In SPI Slave mode:(1) 1 = SSPBUF updates every time that a new data byte is shifted in ignoring the BF bit 0 = If new byte is received with BF bit of the SSPSTAT register already set, SSPOV bit of the SSPCON1 register is set, and the buffer is not updated In I<sup>2</sup>C Master mode and SPI Master mode: This bit is ignored. In I<sup>2</sup>C Slave mode: 1 = SSPBUF is updated and ACK is generated for a received address/data byte, ignoring the state of the SSPOV bit only if the BF bit = 0. 0 = SSPBUF is only updated when SSPOV is clear bit 3 SDAHT: SDA Hold Time Selection bit (I<sup>2</sup>C mode only) 1 = Minimum of 300 ns hold time on SDA after the falling edge of SCL 0 = Minimum of 100 ns hold time on SDA after the falling edge of SCL SBCDE: Slave Mode Bus Collision Detect Enable bit (I<sup>2</sup>C Slave mode only) bit 2 If, on the rising edge of SCL, SDA is sampled low when the module is outputting a high state, the BCL1IF bit of the PIR3 register is set, and bus goes idle 1 = Enable slave bus collision interrupts 0 = Slave bus collision interrupts are disabled bit 1 AHEN: Address Hold Enable bit (I<sup>2</sup>C Slave mode only) 1 = Following the eighth falling edge of SCL for a matching received address byte; CKP bit of the SSPCON1 register will be cleared and the SCL will be held low. 0 = Address holding is disabled **DHEN:** Data Hold Enable bit (I<sup>2</sup>C Slave mode only) bit 0 1 = Following the eighth falling edge of SCL for a received data byte; slave hardware clears the CKP bit of the SSP-CON1 register and SCL is held low. 0 = Data holding is disabled For daisy-chained SPI operation; allows the user to ignore all but the last received byte. SSPOV is still set when a new Note 1:

#### **REGISTER 32-4:** SSP1CON3: SSP1 CONTROL REGISTER 3

- byte is received and BF = 1, but hardware continues to write the most recent byte to SSPBUF.
  - 2: This bit has no effect in Slave modes that Start and Stop condition detection is explicitly listed as enabled.
  - 3: The ACKTIM Status bit is only active when the AHEN bit or DHEN bit is set.

R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
CLKREN	_	_	CLKRI	DC<1:0>	(	CLKRDIV<2:0>	•
bit 7							bit 0
Legend:							
R = Readable I	bit	W = Writable	oit	U = Unimpler	nented bit, read	1 as '0'	
u = Bit is uncha	anged	x = Bit is unkr	own	-n/n = Value a	at POR and BO	R/Value at all o	other Resets
'1' = Bit is set		'0' = Bit is clea	ared				
bit 7	CLKREN: Re	ference Clock	Module Enable	e bit			
	1 = Referen	ce clock modu	e enabled				
	0 = Referen	ce clock modul	e is disabled				
bit 6-5	Unimplement	ted: Read as '	)'				
bit 4-3	CLKRDC<1:0	>: Reference (	Clock Duty Cy	cle bits <sup>(1)</sup>			
	11 = Clock ou	tputs duty cycl	e of 75%				
	10 = Clock out	tputs duty cycl	e of 50%				
	01 = Clock ou	tputs duty cycl	e of 25%				
		itputs duty cyci					
bit 2-0	CLKRDIV<2:0	<b>D&gt;:</b> Reference	Clock Divider	bits			
	111 = Base cl	lock value divid	led by 128				
	110 = Base cl	lock value divid	led by 64				
	101 = Base cl	lock value divid	led by 32 led by 16				
	011 = Base cl	lock value divid	led by 8				
	010 = Base cl	ock value divid	led by 4				
	001 = Base cl	lock value divid	led by 2				
	000 = Base cl	ock value					

## REGISTER 34-1: CLKRCON: REFERENCE CLOCK CONTROL REGISTER

**Note 1:** Bits are valid for reference clock divider values of two or larger, the base clock cannot be further divided.

## TABLE 37-17: ZERO CROSS DETECT (ZCD) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C									
Param. No.	Sym.	Characteristics	Min.	Тур†	Max.	Units	Comments		
ZC01	VPINZC	Voltage on Zero Cross Pin	—	0.75	—	V	$\sim$		
ZC02	IZCD_MAX	Maximum source or sink current	—	_	600	μΑ)			
ZC03	TRESPH	Response Time, Rising Edge	—	1	_	ļus			
	TRESPL	Response Time, Falling Edge	_	1	_	μs			

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

### FIGURE 37-12: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

